

LEAD FRAME WITH SLOTS AND A METHOD FOR MOLDING INTEGRATED CIRCUIT PACKAGES

ABSTRACT OF THE DISCLOSURE

A lead frame (10) is connected to an integrated circuit (32) by adhesives. The lead frame (10) includes a mold gate (40) to provide for constant flow of resin (72) into the mold cavity (66) during encapsulation of the integrated circuit (32). The lead frame (10) also has an air vent (50) to direct air and any excess resin (74) from the mold cavity (66) to a dummy cavity (70).

Figure 1.

This Sheet Has Been Replaced

